

#### **LArTPC Pixel Readout Motivation**

- Conventional LArTPC readout is wire-based, ~4mm wire pitch
  - Multiple 2D readout planes
- 2D readout includes ambiguities and anisotropic responses
- Becomes more problematic in higher rate environments
- 3D pixelated readout overcomes most of these



**BERKELEY LAB** 

X. Qian et al 2018 JINST 13 P05032







2

# **LArTPC Pixel Readout Challenges**

- Note: not all unique to pixel readout
- High **channel count**... ~4mm pixel pitch
  - with manageable data rate
  - with minimal # cables interfacing with cryostat
- Low noise
  - < 1ke<sup>-</sup> for MIP detection
- Cryogenic compatibility
  - Stringent heat dissipation limits, ~100  $\mu$ W/pixel
- Scalability
  - Instrument large areas, O(10<sup>2</sup>-10<sup>3</sup>) m<sup>2</sup>, affordably and practically
- Reliability
  - Applications demand ~100% uptime and long operational periods, O(decades)







#### **The LArPix-v2 Channel**

- 64 channels / ASIC
- Simple front end (no signal shaping)
- Self-triggering discriminator
- Configurable thresholds and integration times
- On-chip digital control





## LArPix-v2 System Components

- Pixel tile PCB containing 1000's of pixels/ft<sup>2</sup> and minimal active components
- LArPix ASIC loaded onto backside of pixel tiles
- Single 34-pin ribbon cable per tile
- PACMAN controller
  - Delivers clean power to 100's of ASICs
  - Establishes I/O with ASICs
  - Handles DAQ and configuration for up to 8 tiles









### LArPix-v2 System Components

Pixel tile PCB containing 1000's of pinning active component of minimal active component component produced by commercially available vendors
 LArPix ASIC loss of produced by commercially available vendors
 Singel available











# Hydra I/O Networking

- 2022 R&D 100 Award
- PISO/POSI pair on every edge for chip-to-chip UART data transmission
  - Digital multiplexing O(10<sup>3</sup>) channels per I/O channel
- Enables configurable network paths to send data in/out
  - Avoid single point failures
- Multiple (4) external links per tile PCB (not pictured)

POSI-external



Configuration commands in.





Data packets out. Kevin Wood - CPAD Workshop 2023



Alternative network to avoid problematic chip.



### **LArPix System Applications**

- DUNE LArTPC Near Detector (ND-LAr)
  - ~14,000,000 pixels across 5x7 array of 3x1x1 m<sup>3</sup> modules
  - Central cathode and 2 pixelated anode planes per module
  - Optically isolated TPCs
- Potentially a "phase 2" DUNE FD module
  - order of magnitude larger than ND
  - 8x8 pixel tile grid compatible with existing protoDUNE-VD infrastructure







#### **2x2 Demonstrator**

- Demonstration of ND-LAr design
- 2x2 array of 1.2 x 0.6 x 0.6 m<sup>3</sup> modules containing >300K pixel channels
- 4 modules operated individually at Bern
  - O(10<sup>8</sup>) cosmic events









#### **2x2 Demonstrator**

- Demonstration of ND-LAr design
- 2x2 array of 1.2 x 0.6 x 0.6 m<sup>3</sup> modules containing >300K pixel channels
- 4 modules operated individually at Bern
  - O(10<sup>8</sup>) cosmic events
- @ Fermilab underground facility (MINOS hall) between repurposed Minerva planes
- Will image neutrino interactions in the GeV-energy regime from the NuMI beam











#### Simulation

BERKELEY LAB



Kevin Wood - CPAD Workshop 2023

11

## **Closing Remarks**

- 2016-2018: LArPix v1 proof of principle ASIC
- 2023-2024: LArPix v2 system deployed in a 2.5 tonne active mass LArTPC neutrino detector including >330,000 channels (2x2 Demonstrator)
- Continuing to develop the system and scale up implementations, stay tuned!

Component	LArPix ASIC	Pixel tile	PACMAN controller
R&D focus	<ul> <li>Correlated double sampling → noise</li> <li>10-bit ADC → resolution</li> <li>Robustness</li> </ul>	<ul> <li>Increase size 60%</li> <li>Optimize pixel pad geometry</li> <li>Shielding layer to reduce inductive</li> </ul>	<ul> <li>10-tile capable</li> <li>Differential analog monitor with ADC</li> </ul>







### **LArPix @ DUNE Near Detector**

- The LArPix ASIC will read out the charge signals from DUNE near detector LArTPC component, ND-LAr
- ~15 million channels (3.8 x 3.8 mm<sup>2</sup> pixel pads) readout by ~0.25 million ASICs





# **ArgonCube Design**

- Modular approach, O(50 cm) drifts
- Central cathode provides drift field for 2 optically isolated TPCs
- Resistive shell field cage
- Light detection modules installed along the field cage
- Anode planes outfitted with tiles of PCB components containing gold-plated pixel pads on one side and LArPix ASICs on the other





### **LArPix Readout System Overview**

Item	Quantity for 2x2	Quantity for FSD module	Quantity for ND-LAr
LArPix ASIC	6,400 + 3,200	6,400 + 3,200	224,000 + ~100,000 (Actual spare count will be based on ASIC yield of first production wafer run)
Tile PCB	64 + 16 (100 ASICs/Tile)	40 + 10 (160 ASICs/Tile)	1,400 + 280 (160 ASICs/Tile)
Pacman	8 + 4	4 + 2 + 4	140 + 20
Cryogenic cables	64 + 8	40 + 10	1,400 + 280
Feedthrough assembly	8 + 8	2 + 2	70 + 7



#### **1.2 MW LBNF Spill on ND-LAr**



